

A<sup>1</sup>  
Conclusion

PRELIMINARY AMENDMENT  
New U.S. Application for PCT/JP99/05003

19. An electroless plating process which comprises immersing a substrate in the electroless plating solution according to Claim 14 and performing electroless copper plating at a deposition rate set to 1 to 2  $\mu\text{m}/\text{hour}$ .

A<sup>2</sup>

21. A process for manufacturing a printed circuit board which comprises immersing a resin insulating substrate board in the electroless plating solution according to Claim 14 and performing electroless copper plating at a deposition rate set to 1 to 2  $\mu\text{m}/\text{hour}$  to provide a conductor circuit.

A<sup>3</sup>

44. The multilayer printed circuit board according to Claim 40 wherein said lower-layer via holes are filled with metal.

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